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ACES 2011 Thursday 10<sup>th</sup> of March  
Trackers Upgrade for Phase 2

# Strips Readout Architecture and ABCN 130 nm Front-End ASIC

Speaker : F. Anghinolfi

Krakow, Penn U., CERN, Geneva U., RAL,  
Birmingham, KEK, UCL, UCSC ....

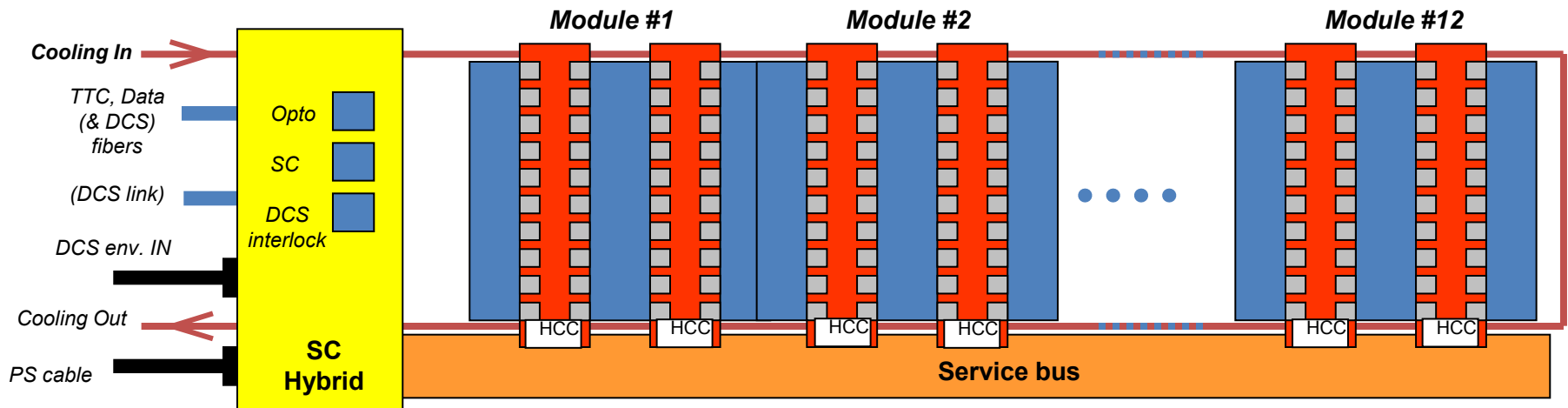
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# To situate the project

- **Replacement of the existing ABCN25 (CMOS 250nm) for prototyping of Silicon strips stave/module construction**
  - ✓ **More realistic power schema (1.3V instead of 2.5V)**
  - ✓ **256 channels (strips) instead of 128 per ASIC (material reduction)**
- **Major Changes**
  - ✓ **L0/L1 data flow control (Track Trigger)**
  - ✓ **Fixed size Data packet format (1 or 2 cluster/packet, robust against harsh environment)**

# ATLAS Strips Readout Concept (Barrel)

ACES 2009

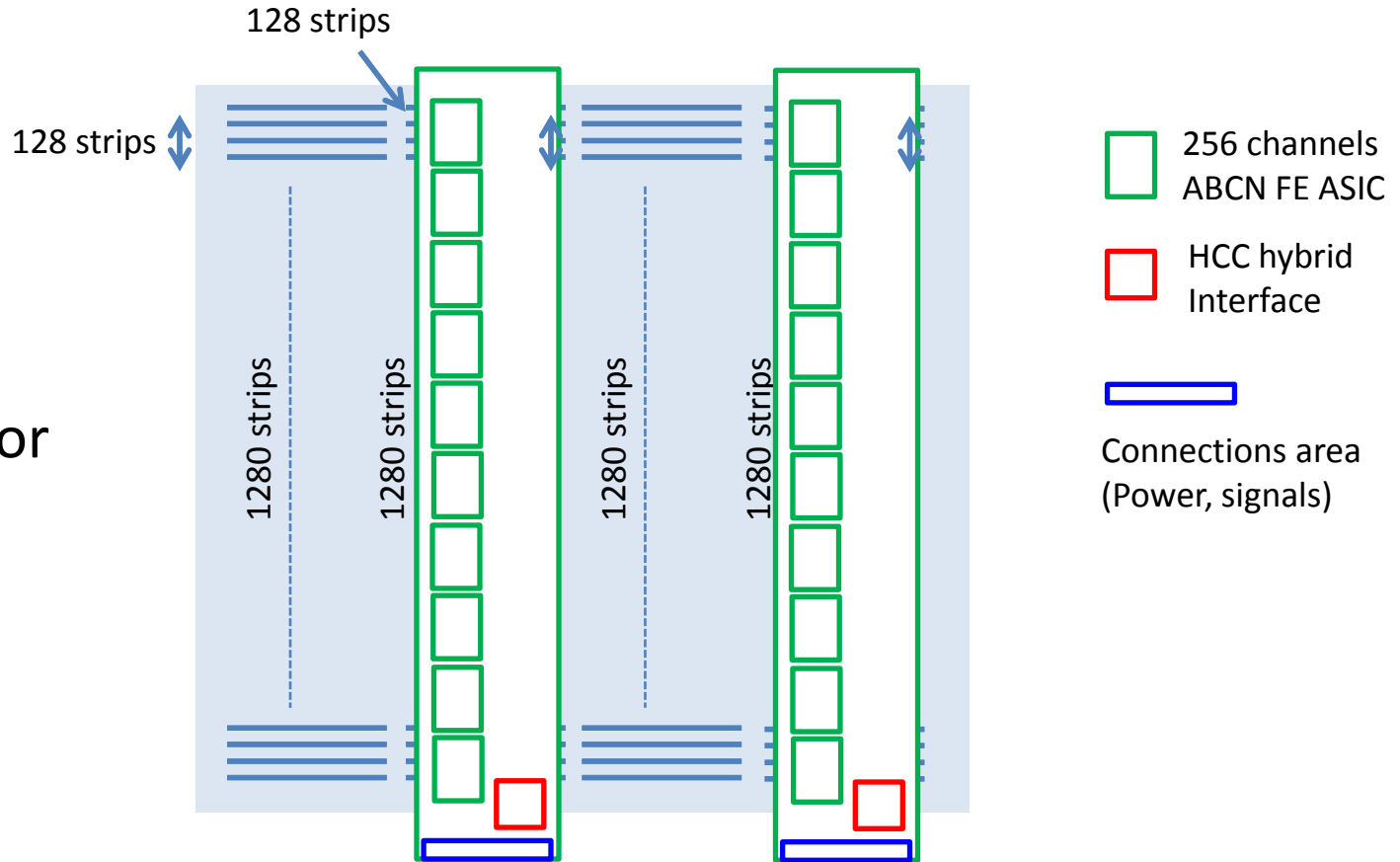


Barrel “short” strips stave : 12 sensors of  $\sim 10 \times 10 \text{ cm}$

Sensor : 1280 strips with  $\sim 80$  microns pitch per row  
4 rows with  $\sim 2.5$  centimeters strip length

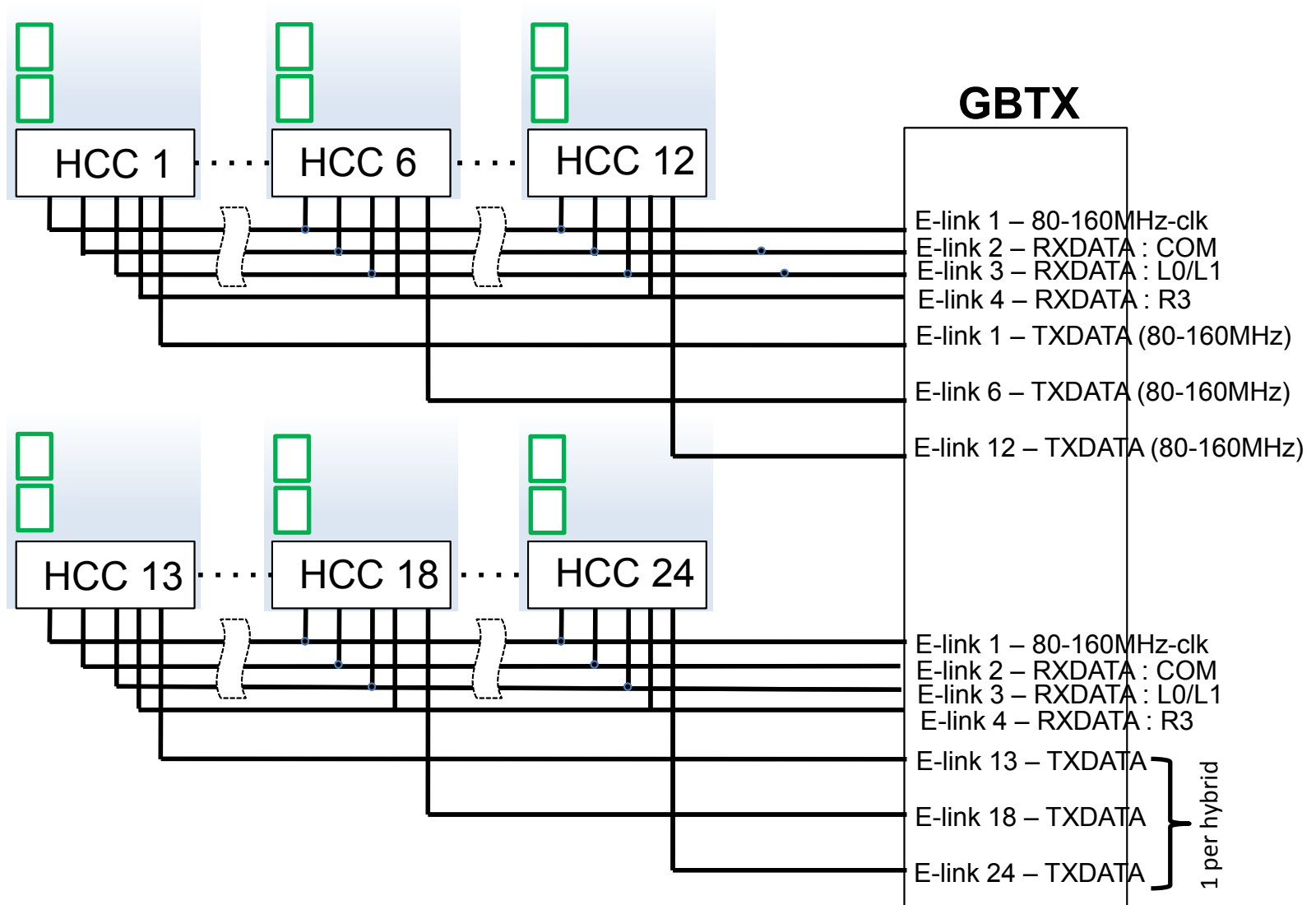
# Short Strips Hybrid model

Hybrid over strips detector



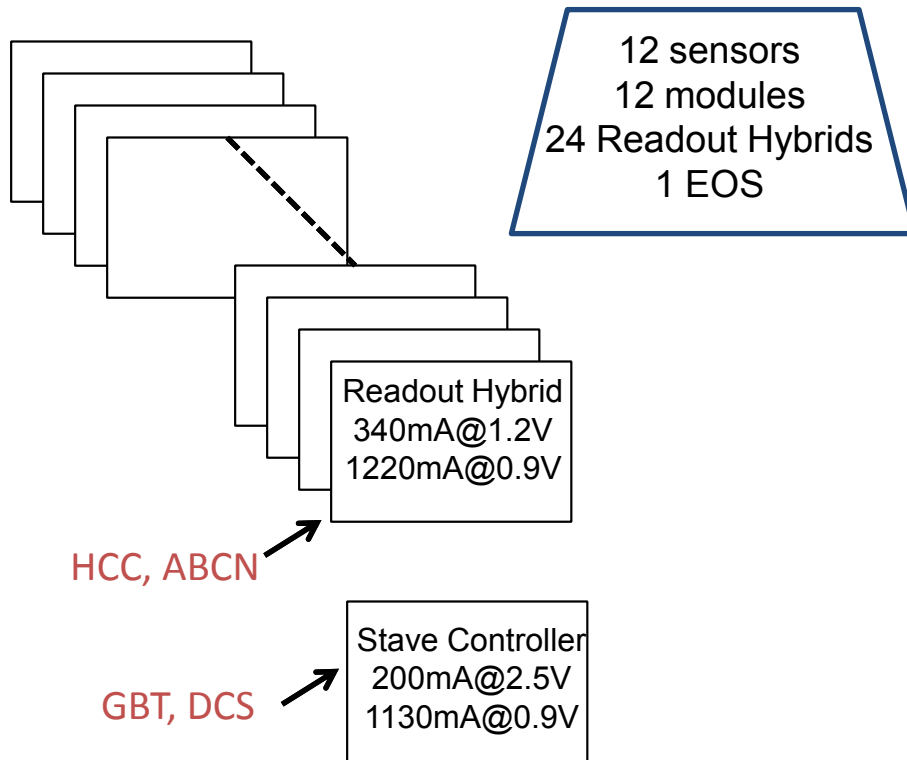
Recent proposal : 256 channels per FE ASIC (10 ABCN per Hybrid)

# Hybrid readout through the GBT system



E-link connections btw. 12 modules (24 Hybrids) to GBTX e-links

# Power estimates for one short strips single side stave

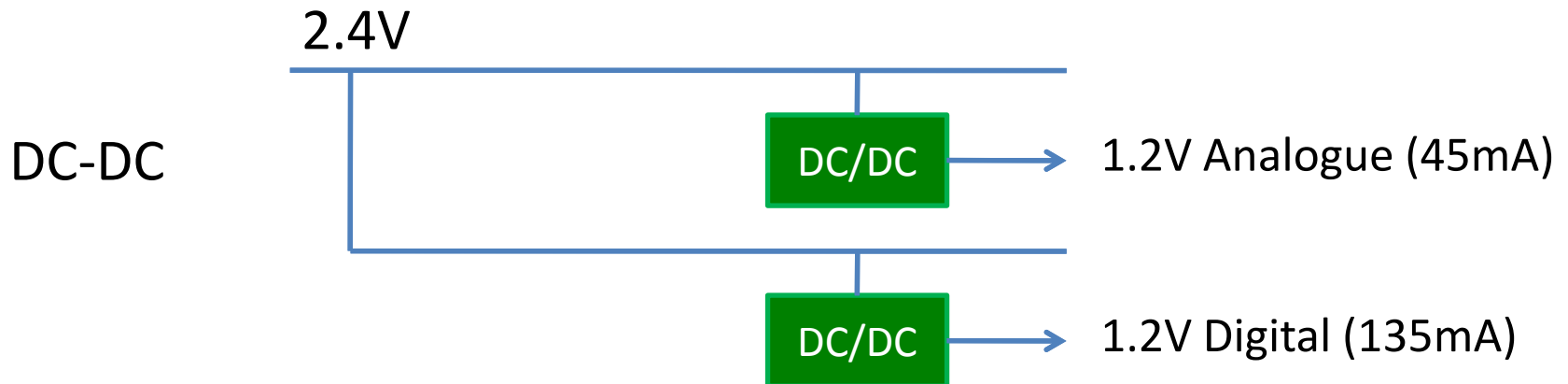
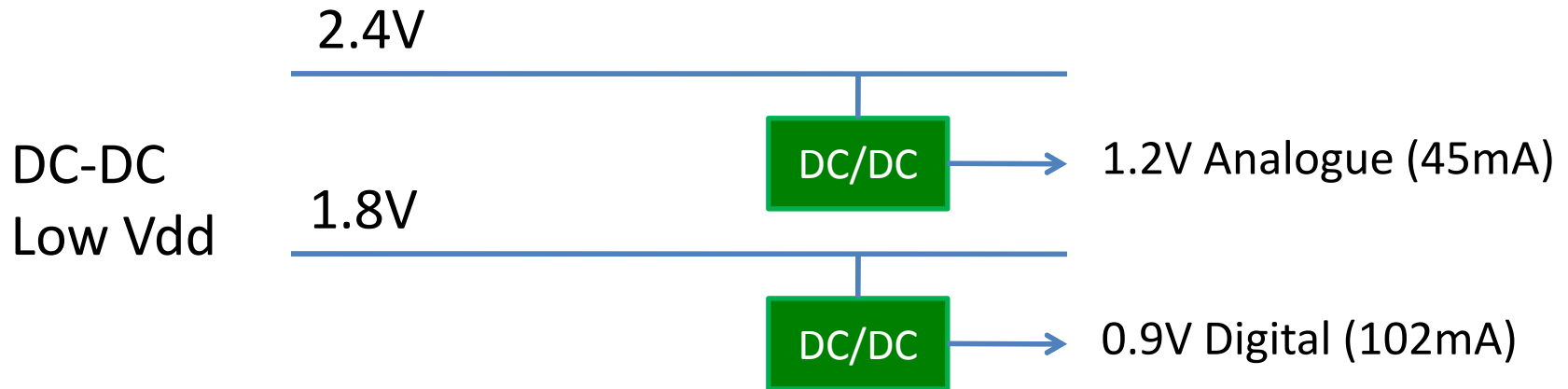


@Vddd = 0.9v	Current	Power
DC-DC	4.1 A	48.6 W
Serial Power	1.8 A	54.9 W

One example for Power numbers, single-side stave with short strips.  
Several variants exist

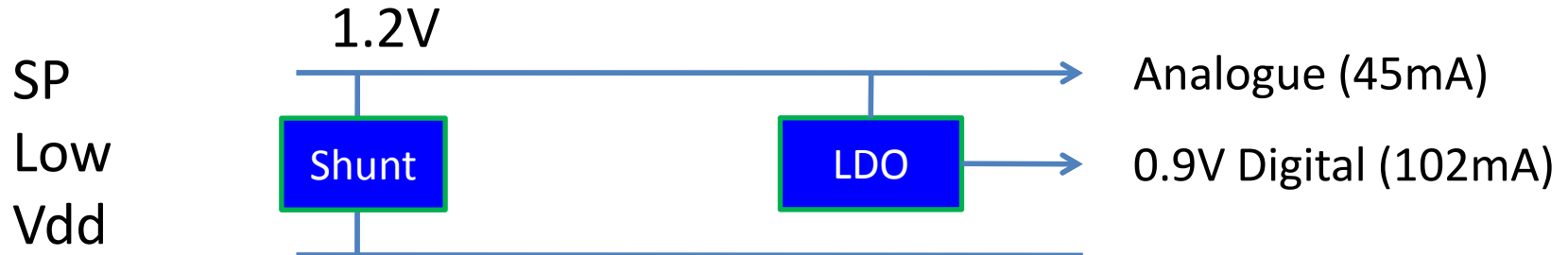
Using VDD digital at 0.9V will be reconsidered after measurements of the SEU cross-section versus VDD

# ABCN-130 Powering Schema DC-DC options



There are discussions on placing the DC-DC converters on-chip or on a separate flip-chip

# ABCN-130 Powering Serial Power (SP) options



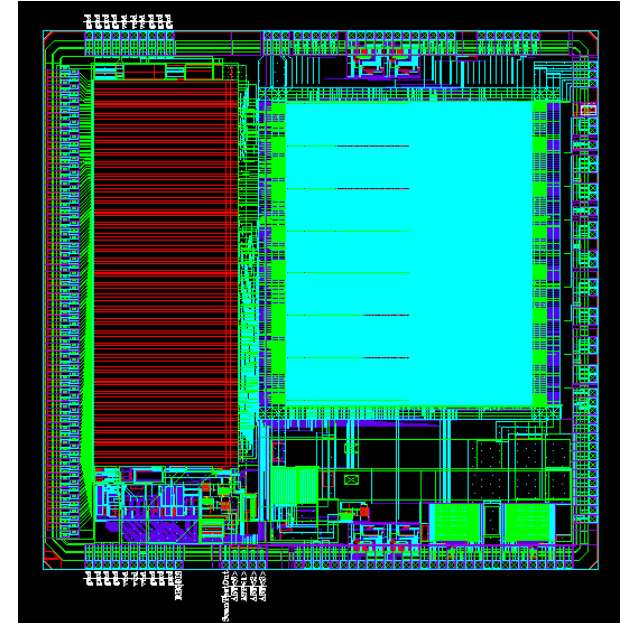
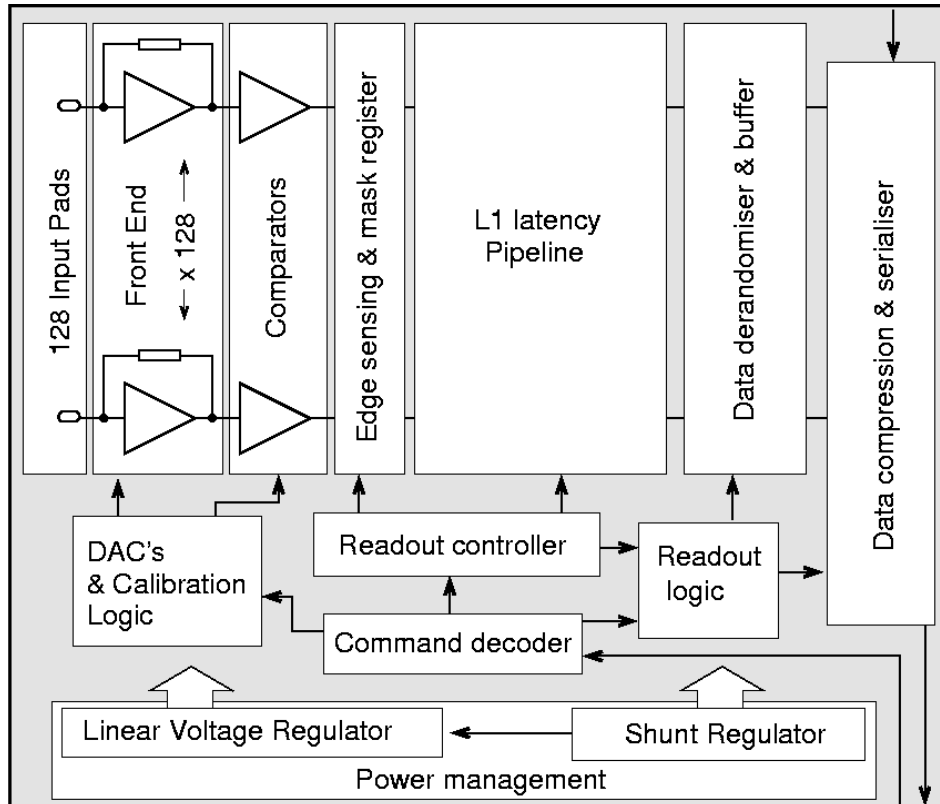
The shunt device is distributed across FE chips, controlled by a common feedback loop



# Towards ABCN 130 implementation

- The present ABCN25 realization
- Elements for ABCN 130
- New features in ABCN 130

# ABCN25 Strips Readout Asic



7.7 x 7.5 mm<sup>2</sup>

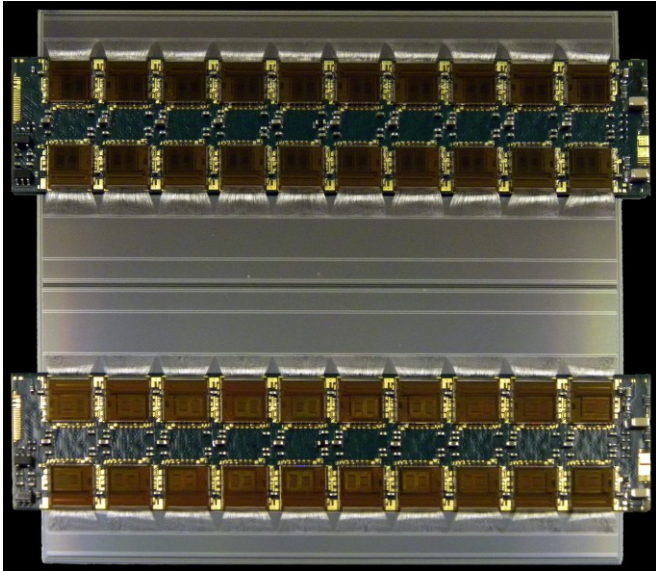
128 channels

35mA @ 2.0V Analogue

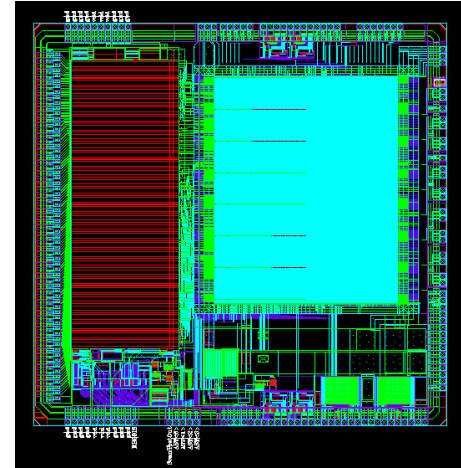
135mA @ 2.5V Digital

Existing vehicle for hybrid/module/stave developments

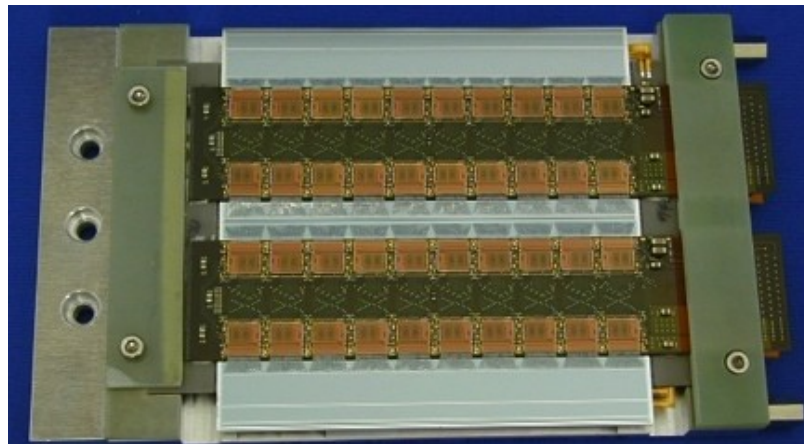
# ABCN25 Strips Readout on Hybrids



US/UK version



Modules and stavelets are tested with both serial or DC/DC powering systems (but 2.5V)



GVA-KEK version

# ABCN 130nm : What is new/changed ?

- ✧ 256 channels (strips) per ASIC
- ✧ Dual Trigger (L0/L1) data flow control
- ✧ Fixed size data packet per ASIC
- ✧ Extended SEU protection (not commented here)

## Maintained :

- ✧ Serial or DC/DC power schema compatible

# ABCN 130nm : Front-End Prototype

## 130nm Front-end (J. Kaplon)

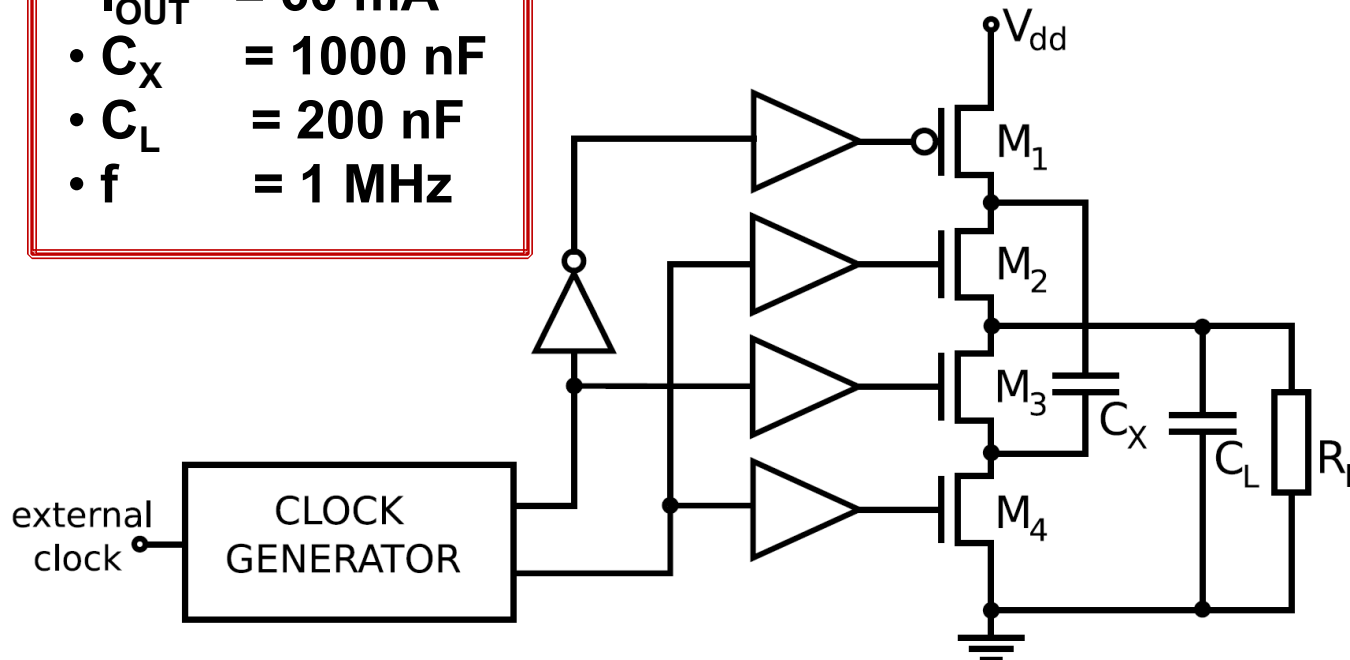
- Channel 22 $\mu$ m x 700 $\mu$ m (w/o bonding pad area)
- Gain 100mV/fC
- Linear range 4fC (saturation at 6fC)
- Peaking time 22ns
- Current consumption of the front end channel;  $I_{input}+80\mu$ A (input = 100-160 $\mu$ A)
- Power consumption @ 1.2V : 220 – 290 $\mu$ W / channel
- Noise estimates  $\longrightarrow$

Det. Cap	I_leakage	I_input	ENC
5p	0	100 $\mu$ A	800e-
5p	600nA	100 $\mu$ A	850e-
10p	0	160 $\mu$ A	1000e-
10p	1.3 $\mu$ A	160 $\mu$ A	1150e-

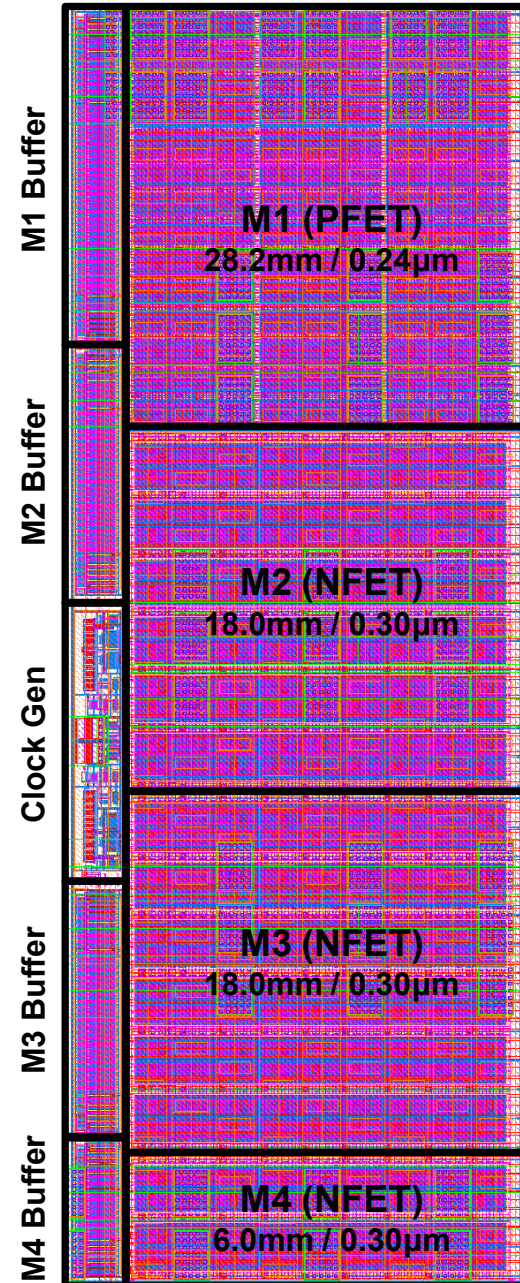
# ABCN 130nm : DC/DC prototype

- $V_{DD} = 1.9 \text{ V}$
- $V_{OUT} = 926 \text{ mV}$
- $I_{OUT} = 60 \text{ mA}$
- $C_X = 1000 \text{ nF}$
- $C_L = 200 \text{ nF}$
- $f = 1 \text{ MHz}$

**Power Efficiency = 97%**  
(including all circuitry)



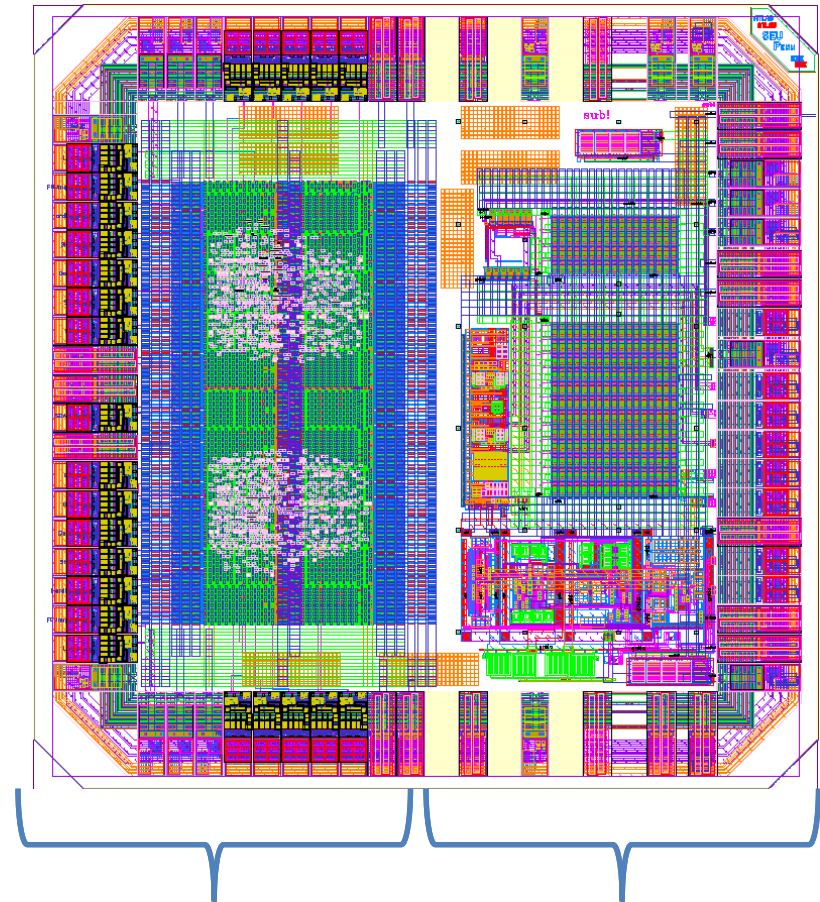
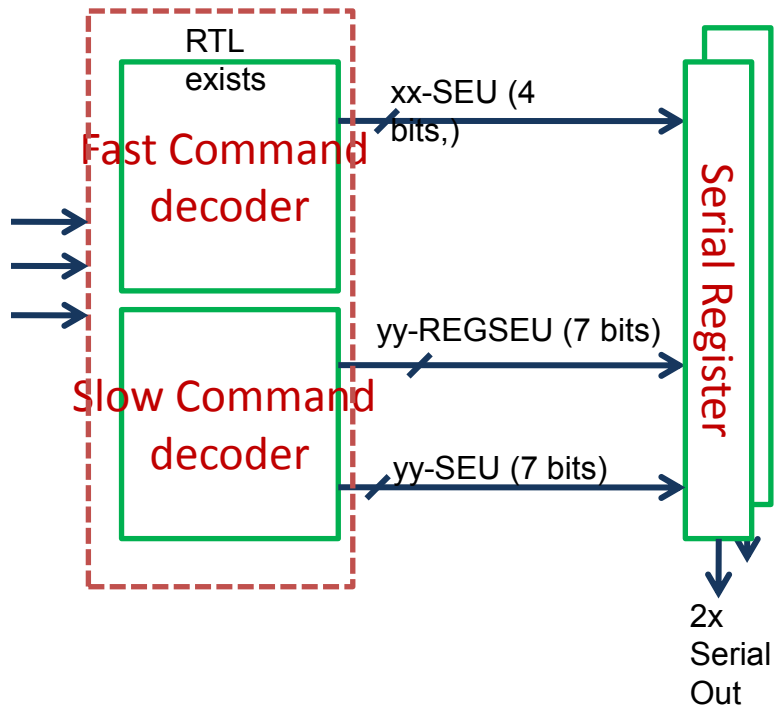
**Step-Down converter design**  
**M. Bochenek**





# ABCN 130nm : SEU Logic prototype

## SEU Logic circuit



SEU Logic part  
(F. Anghinolfi,  
K. Swientek)

SPP Elements  
(M. Newcomer,  
N. Dressnandt)

# ABCN 130nm : L0/L1 Data Flow Control

An early “fixed” latency L0 trigger is received by all FE Asics

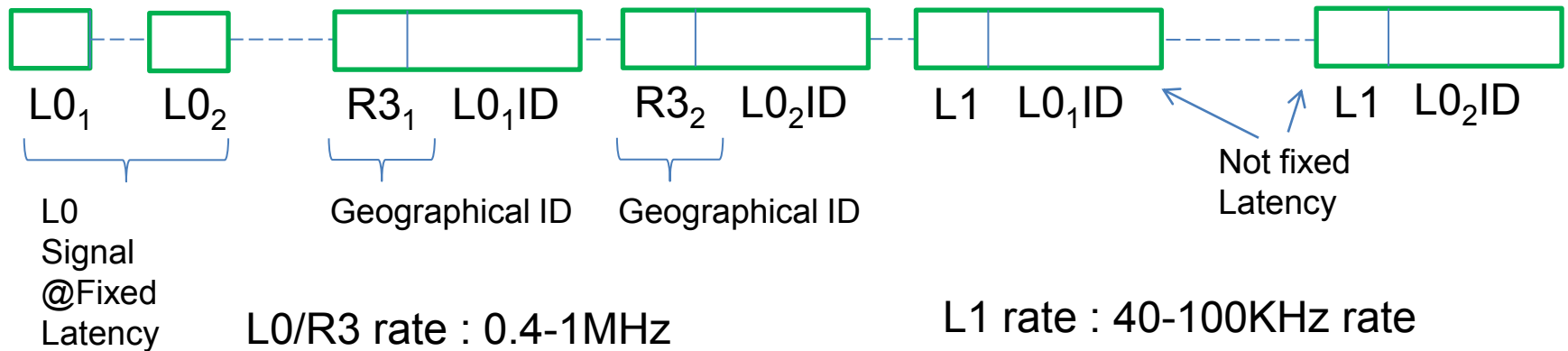
A fraction of the detector (10%) receives a Readout Region Request (R3) to readout hit patterns relative to one L0

At reception of an L1 trigger tagged with L0 identifier, the whole detector is readout



# ABCN 130nm : L0/L1 Data Flow Control

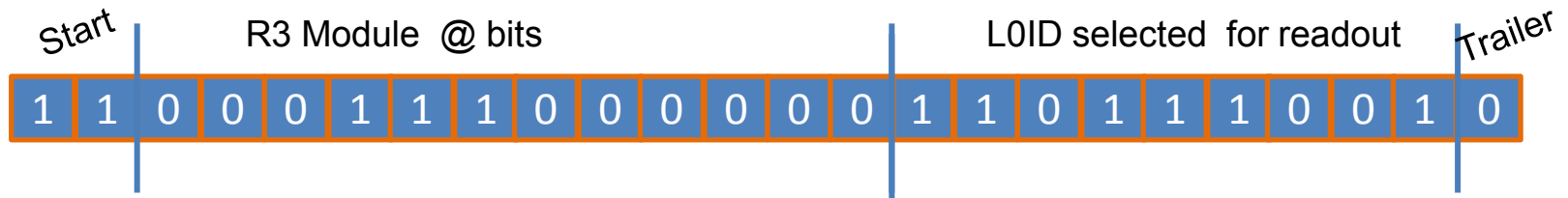
Trigger command with L0/L1 capability



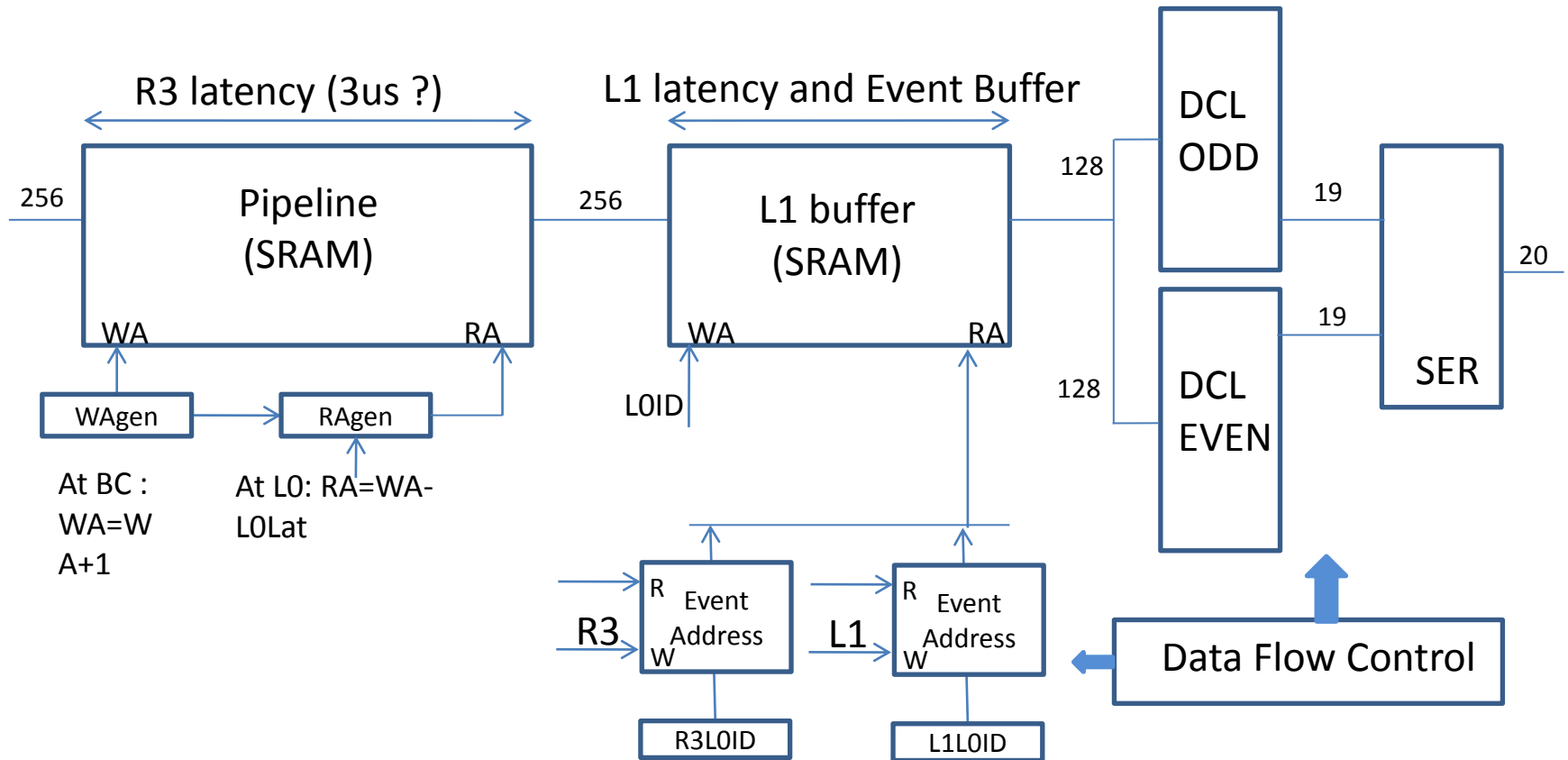
Physically there are 2 x 80Mbits/s lines carrying the above information :

L0/L1 : L0 bit sync with one phase of BC, L1 bit with the other phase of BC

R3 : R3 Packets (Header + Geo address + L0ID)



# ABCN 130nm : L0/L1 data Flow Control



Radiation tolerant (TID & SEU) SRAM design by CERN/MicroElectronics

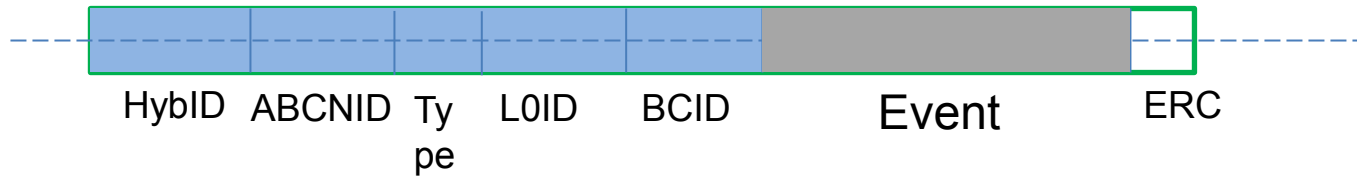
# ABCN 130nm : Data Packets

- In previous ABCD/ABCN : Data packets are built with data from adjacent chips (data concatenation built with a time constrained token signal, data packet built by a “Master” function)
- Now it is proposed “Independent Fixed size Data packets” per ABCN chip : it has impact on BW, but independent data packet carry its complete identification pattern : corruption means one packet loss only. One packet payload has room for one or two\* hit/cluster physics data of the same event.

\* : still under discussion

# ABCN 130nm : Data Packets

## Data Packet Proposal



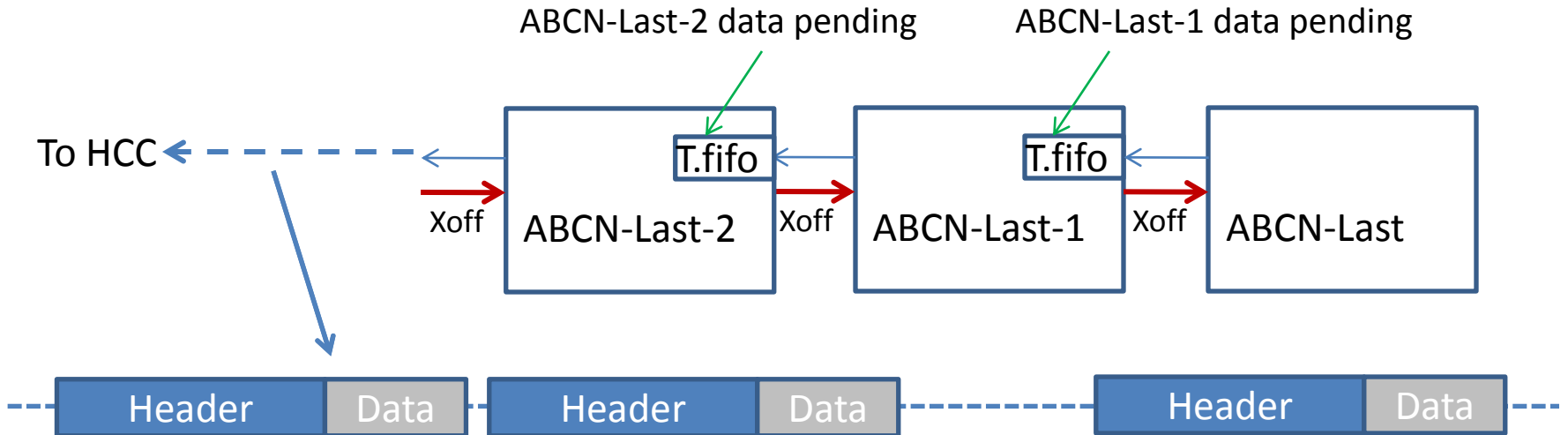
<b>Hybrid_ID</b>	5 bits	24 hybrids per half single sided stave
<b>ABCn_ID</b>	4 bits	10 ABCn per hybrid
<b>Data_Type</b>	3 bits	L1 data, L0 data, registers, etc.
<b>L0ID</b>	8 bits	Should be large enough to cover the L1 latency. Assumed 1MHz L0 rate, 256 $\mu$ s latency
<b>BCID</b>	8 bits	12 would be safer but 8 are sufficient as it is used in conjunction with L0ID
<b>Total</b>		<b>28 bits</b>

Strip_ID	8 bits
BC n-1 n n+1 for Strip_ID	3 bits
BC n-1 n n+1 for Strip_ID+1	3 bits
BC n-1 n n+1 for Strip_ID+2	3 bits
BC n-1 n n+1 for Strip_ID+3	3 bits
<b>Total</b>	<b>20 bits</b>

Preformat for 4 adjacent channels : <mean> cluster size 2.35

# ABCN 130nm : Data Packets Transmission

Data is passing in a daisy-chain formed by a group of 5 chips on the hybrid.  
Data is passing to the HCC and from there sent through the GBT system

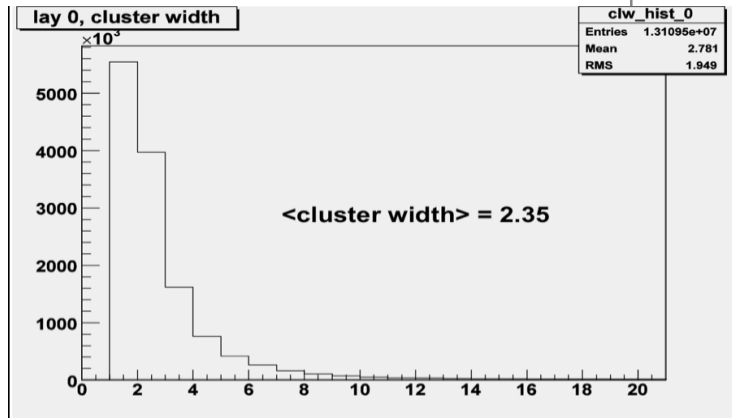
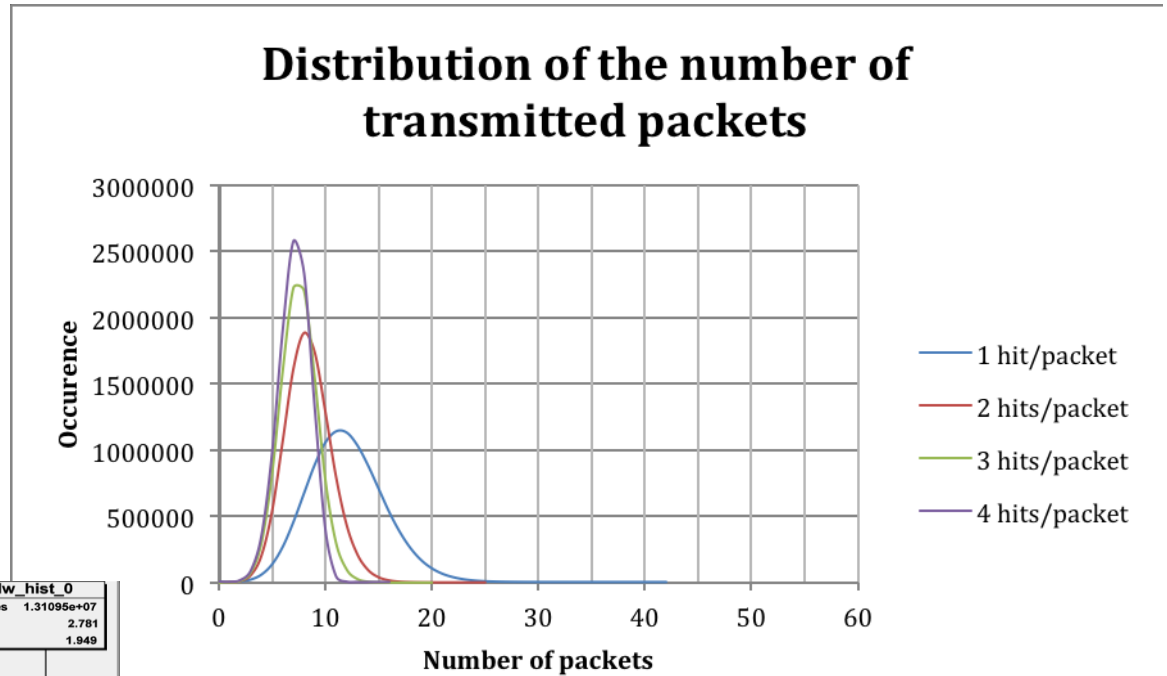


Xoff control : no timing constraint, one FIFO and some add. Logic in each chip,  
readout starts from last chip of the chain

# ABCN 130nm : Data Packets Transmission

#hits in 256 ch	Probability
0	0.111
1	0.222
2	0.238
3	0.190
4	0.132
5	0.068
6	0.027
7	0.009
8	0.002

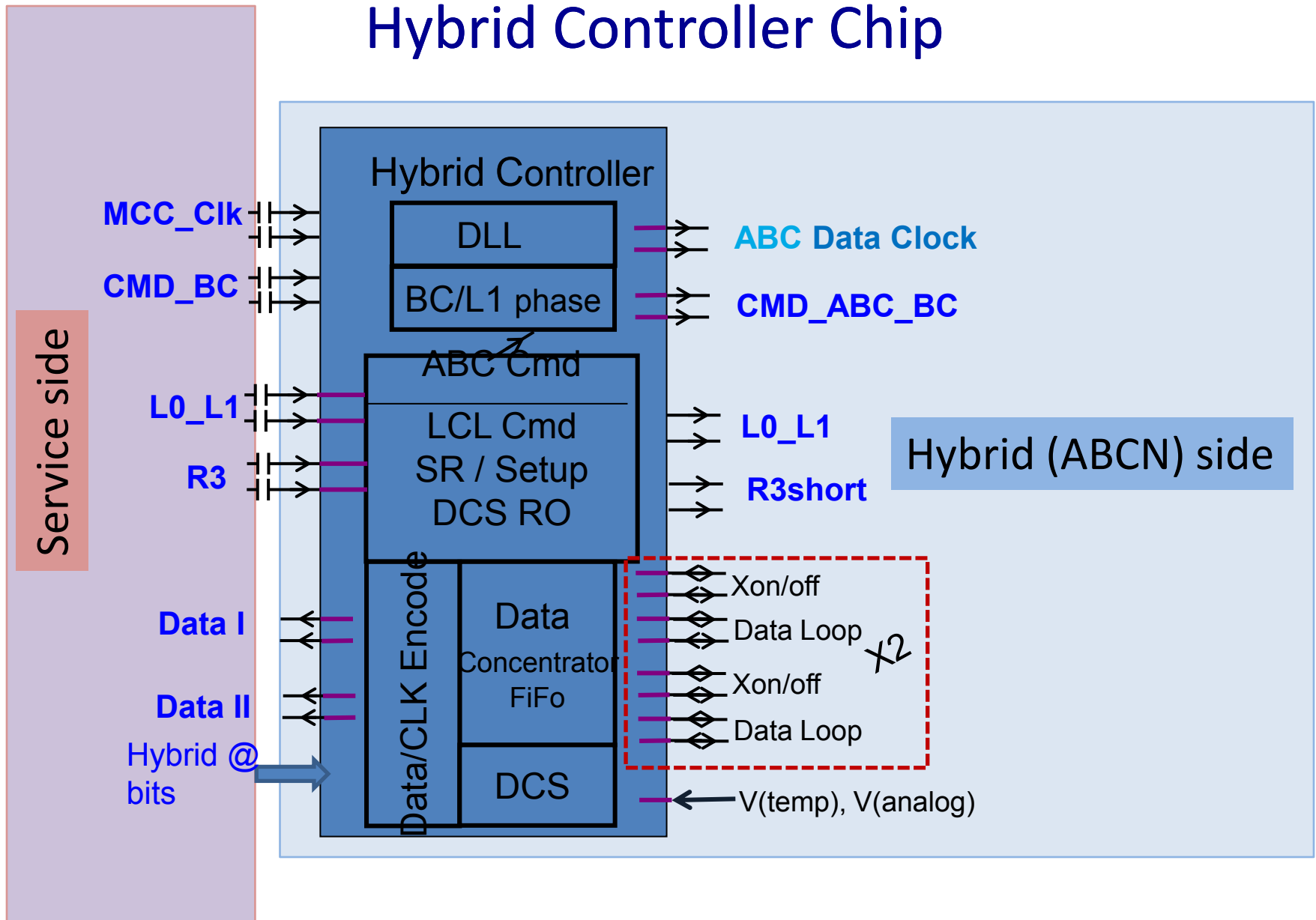
Simplified model giving the number of hits distribution in a 256-channel ABCN for a  $5.10^{34} \text{ cm}^{-2} \cdot \text{s}^{-2}$  luminosity



Distribution of the number of packets transmitted by a readout hybrid in the case a packet contains 1, 2, 3 or 4 hits for a  $5.10^{34} \text{ cm}^{-2} \cdot \text{s}^{-2}$  luminosity (100K events).

To be confirmed : only extrapolation from 128 channels case

# Hybrid Controller Chip



# ABCN-130 : Projection

Actually building specifications together with new functionality

Analogue Front-End well under control

Powering schema not fixed

Digital parts adapted for Track Trigger/Data reduction

Less than 1mW per channel ABCN budget

New event data transmission schema

Expected “readiness” 2nd semester 2012

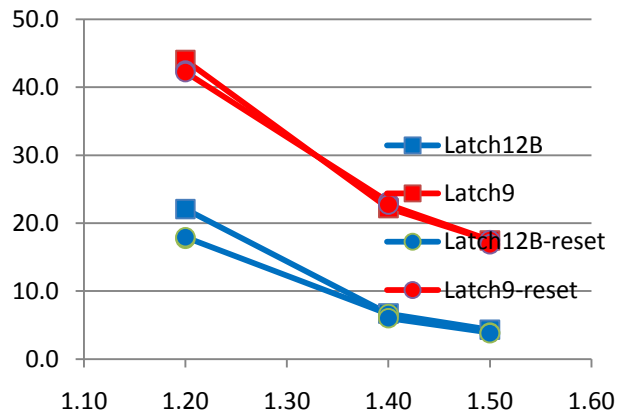


# Backup Slide

# 130nm SEU cross section

(Data from the Pixel Group)

- What was tested : {Standard ARM}, {DICE}, {DICE + Triplication}
- What was tested : dependence over VDD (x5-10 in the range 1-1.5V)



STD	DICE	DICE triplication
5E-15	1-5E-16	<E-17

(My) Approx of Pixel SEU Test results, should be verified

- What (has to) should be tested : {Standard IBM}, {Standard IBM + triplication}, {DICE with IBM-like cell}, all with T3 layout now